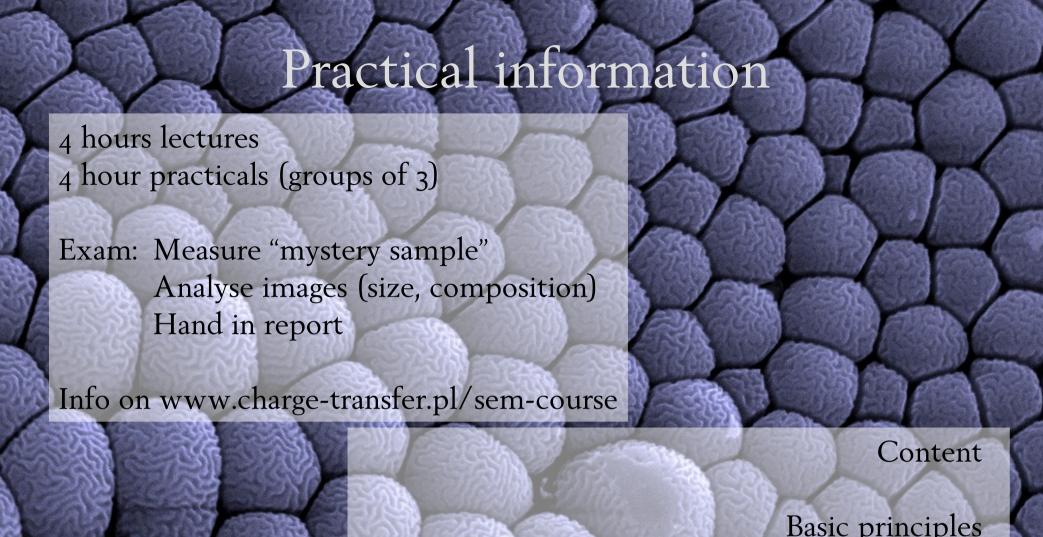
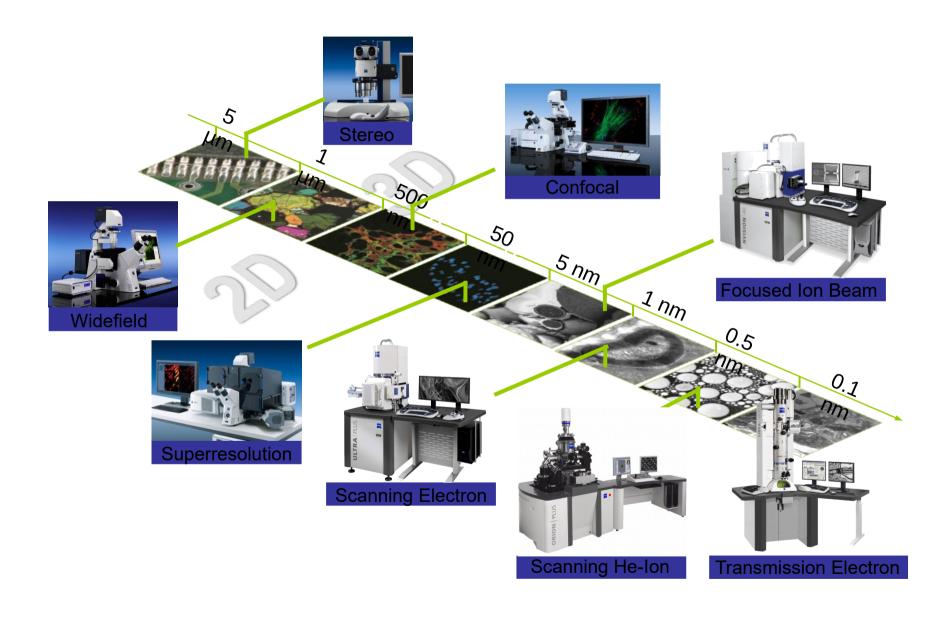
A practical introduction to scanning electron microscopy

Martin Jönsson-Niedziółka – martinj@ichf.edu.pl

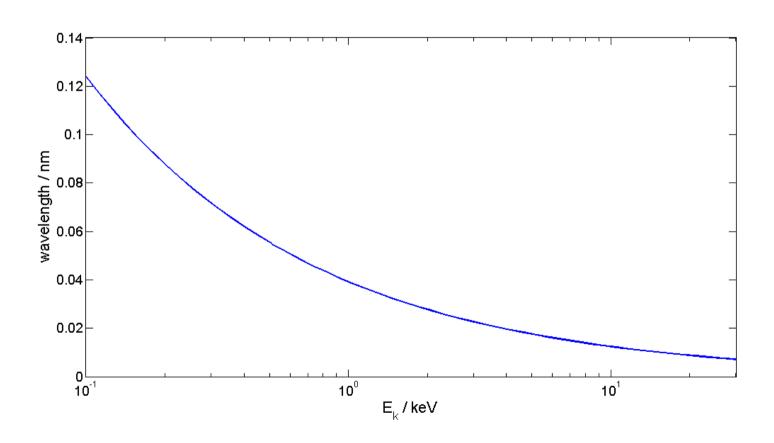


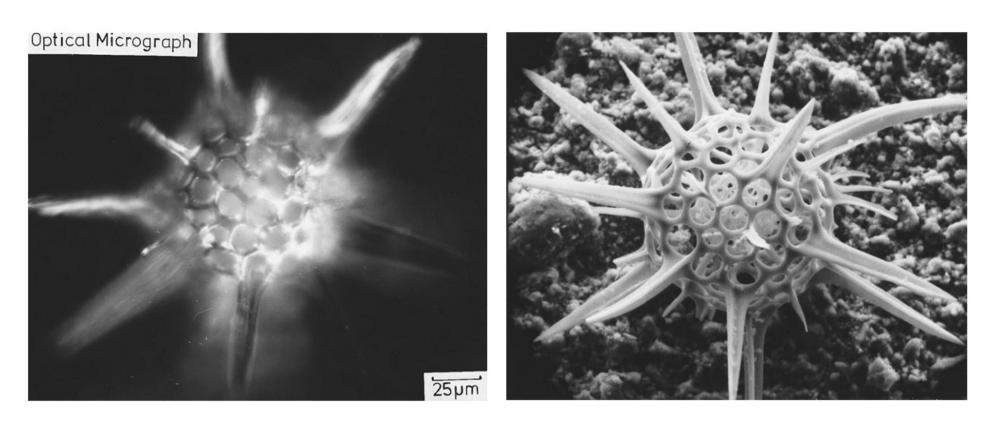
Basic principles
Electron-matter interaction
Settings and limitations
Different detection modes
Our system
Sample preparation
EDX / WDX



de Broglie wave-length

$$\lambda = \frac{h}{\sqrt{2mE_{kin}}} \approx \frac{1.23}{\sqrt{E_{kin}}}$$
 nm

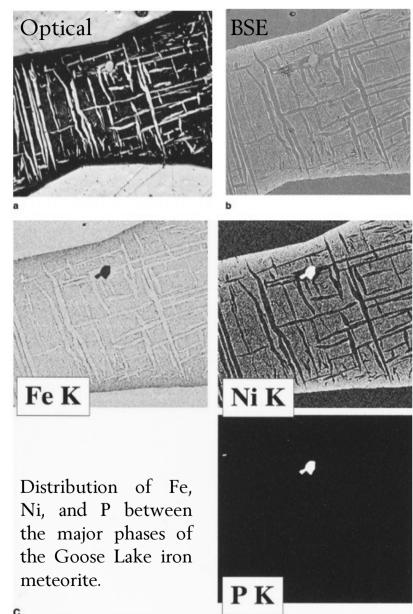




Optical and SEM micrograph of the radiolarian Trochodiscus longispinus

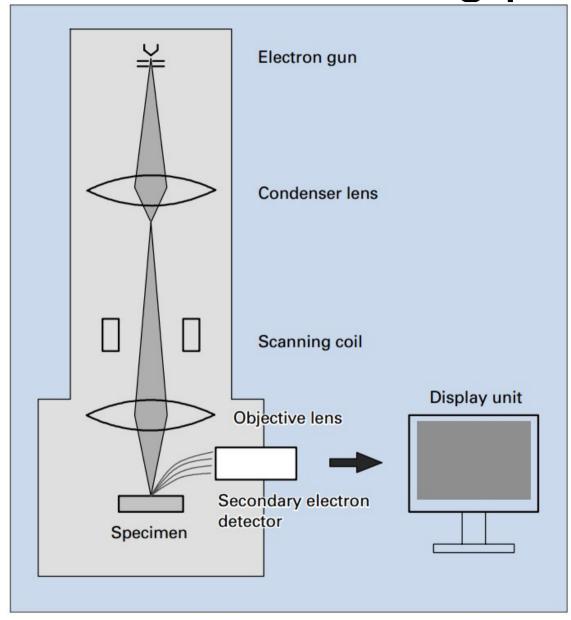
Source: Goldstein

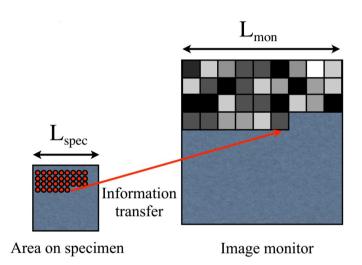
- Versatile
 - Topography
 - Elemental information
 - Crystallinity
- Fast
- Non-descructive (mostly)
- Easy (mostly)



Source: Goldstein

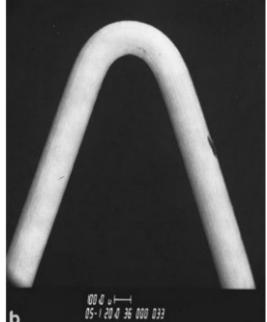
Working principle



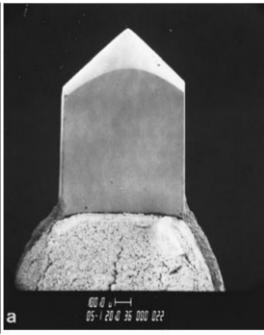


Electron gun

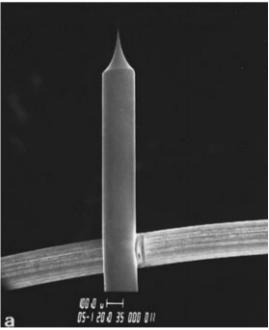
	TE gun		FE gun	SE gun
	Tungsten	LaB ₆	re guii	SE guii
Electron-source size	15 ~ 20 μm	10 μm	5 ~ 10nm	15 ~ 20nm
Brightness (Acm ⁻² rad ⁻²)	10 ⁵	10 ⁶	108	108
Energy spread (eV)	3~4	2~3	0.3	0.7 ~ 1
Lifetime	50 h	500 h	Several years	1 to 2 years
Cathode temperature (K)	2800	1900	300	1800
Current fluctuation (per hour)	<1%	<2%	>10%	<1%



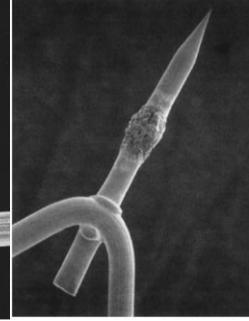
Tungsten wire thermionic emitter



Lanthanum hexaboride thermionic emitter



Tungsten singly-crystal cold field emission tip



 $\label{eq:continuity} \begin{aligned} & \text{Tungsten/ZrO}_{_2} \text{ Schottky field} \\ & \text{emission tip} \end{aligned}$

Source: Goldstein

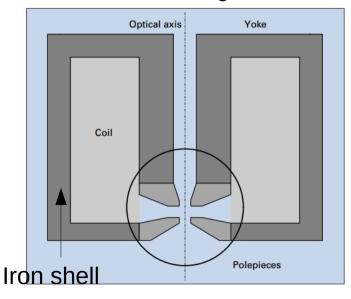
Electron lenses

In SEM magnetic lenses are used. Cylindrically symmetric "Soft magnetic" shell Field leaks out at narrow gap. Only the pole pieces need to be very accurately fabricated

Focal length of the lens can be changed

$$f \approx V_0 / (NI)^2$$

Beam is twisted through the lens



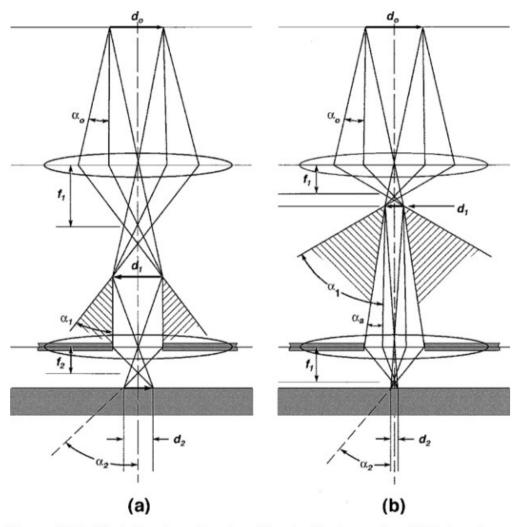


Figure 2.20. Effect of condenser lens strength in a two-lens lens system. (a) Weak condenser lens, (b) strong condenser lens.

Strong lens ('large spot') → Higher current

- → Lower resolution

Objective lens

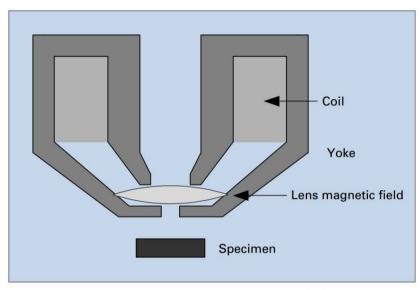


Fig. 34 Construction of the conventional objective lens.

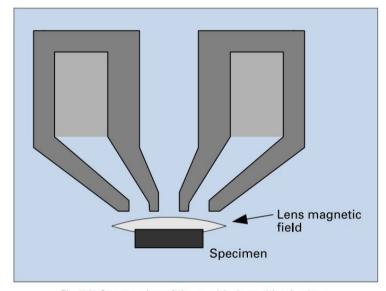


Fig. 36 Construction of the semi-in-lens objective lens. **Snorkel**

snorkel immersion

Lens magnetic field Specimen

Fig. 35 Construction of the in-lens objective lens.

Snorkel:

- Higher resolution
- Lower max field of view (min ca 1500x)
- Only in-lens detector
- Limit on usable voltages

WD / mm	E_{max} / kV
1	1.2
2	3.5
3	7
4	12
5	18
6	24
7	30

Limits on resolution

Resolution is given by probe diameter (size of electron beam)

• Gaussian beam diameter (no aberration)

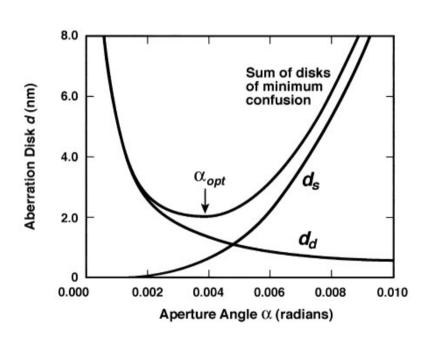
$$d_{\rm G} = \sqrt{\frac{4i_{\rm p}}{\beta\pi^2\alpha_{\rm p}^2}}$$

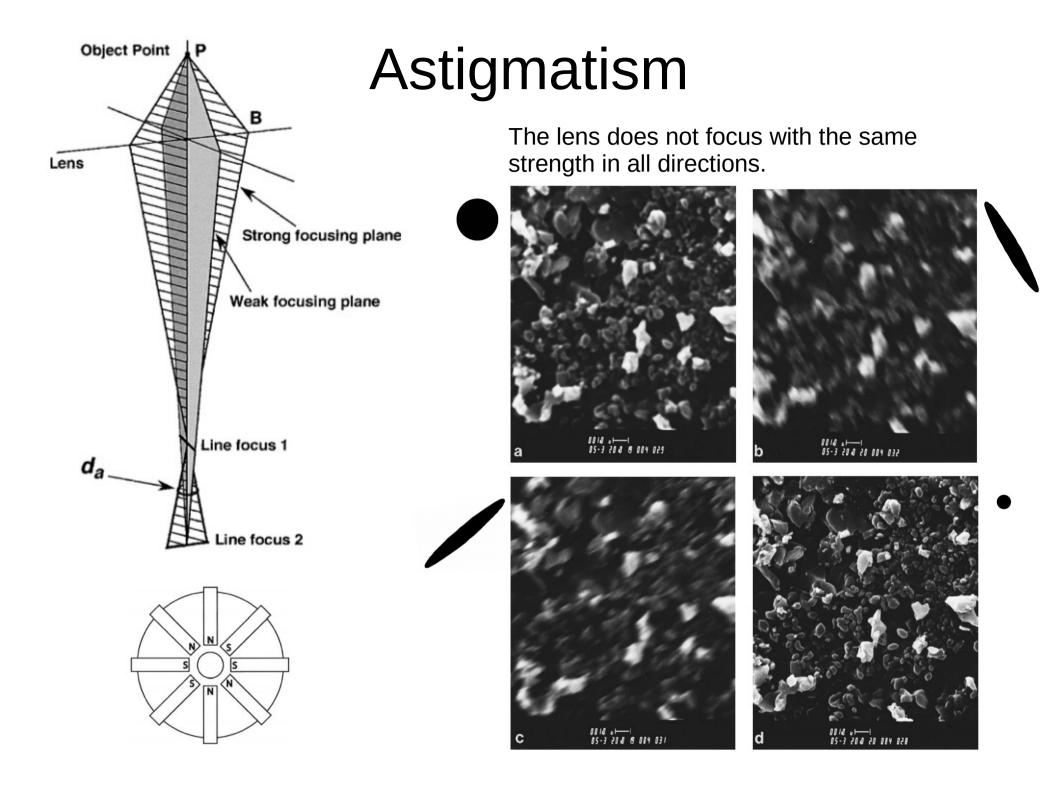
- Diffraction in aperture
- Spherical aberration

$$d_{\rm s} = \frac{1}{2}C_{\rm s}\alpha^3,$$
Almost prop to f

Chromatic aberration

$$d_{\rm c} = C_{\rm c} \alpha \left(\frac{\Delta E}{E_0} \right)$$





A game of compromises

High High resolution Unclear surface structures More damage More charging More edge effect Accelerating voltage Clear surface structures Less damage Less charging Lower resolution Less edge effect Low

A game of compromises

Small High resolution Smaller depth of field Working distance Larger depth of field Wider field of view Lower resolution Large

A game of compromises

Better count rate (esp. important for EDX/WDX)

"Cleaner" image

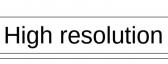
High

Lower resolution

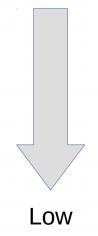
Smaller depth of field

More charging

Current



Larger depth of field

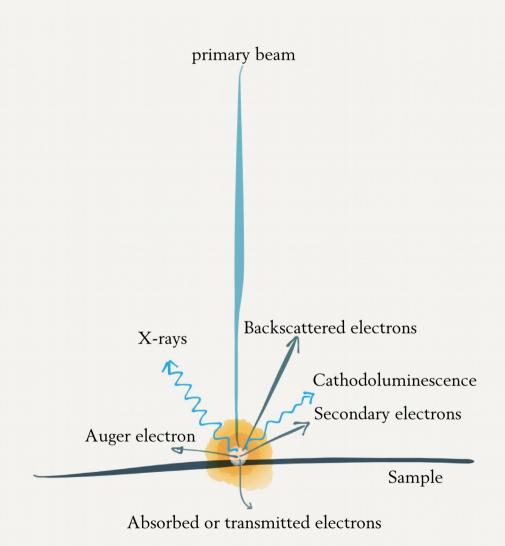


Noisier image



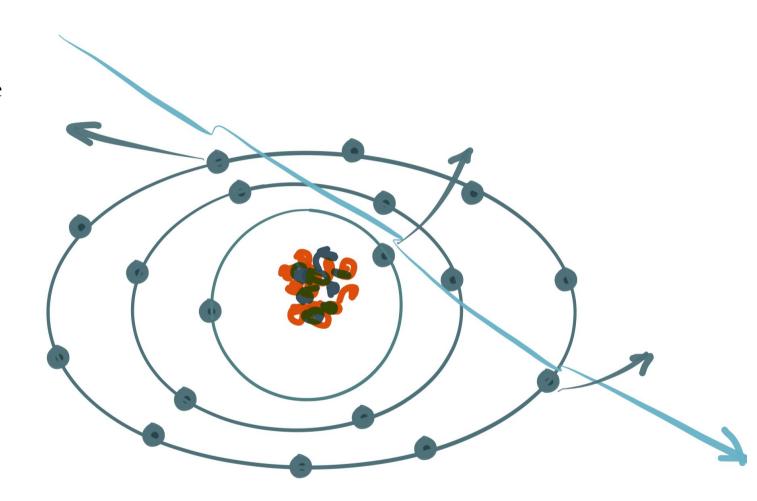


Electron matter interaction



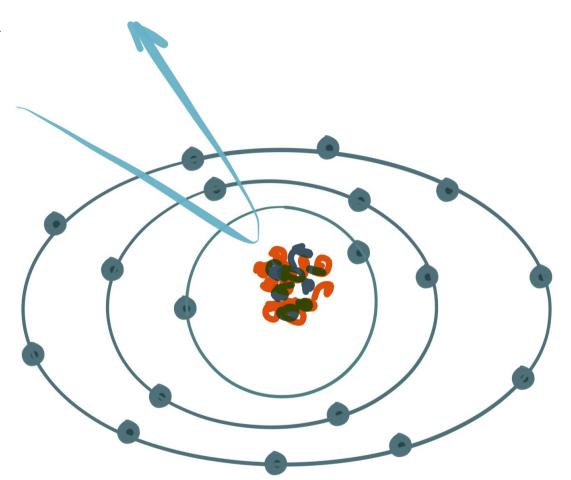
Secondary electrons

- Non-elastic collision
- Electrons come from inside the atoms in the sample.
- Low energy
- Information about surface topography



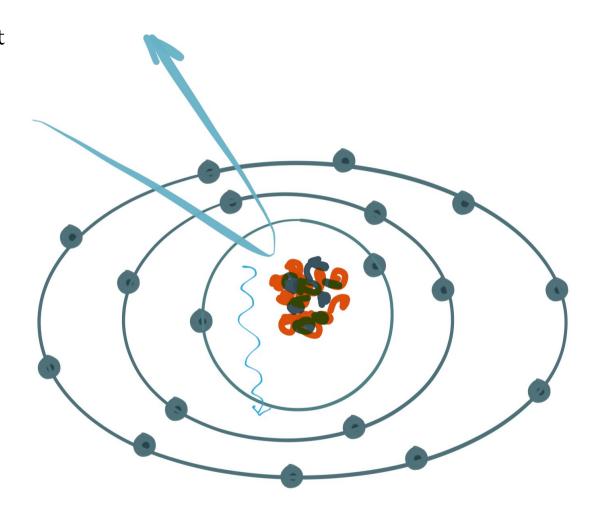
Backscattered electrons

- (Almost) elastic collision
- Electrons come from the primary beam.
- High energy
- Probes deeper into the sample
- Some information about elemental composition



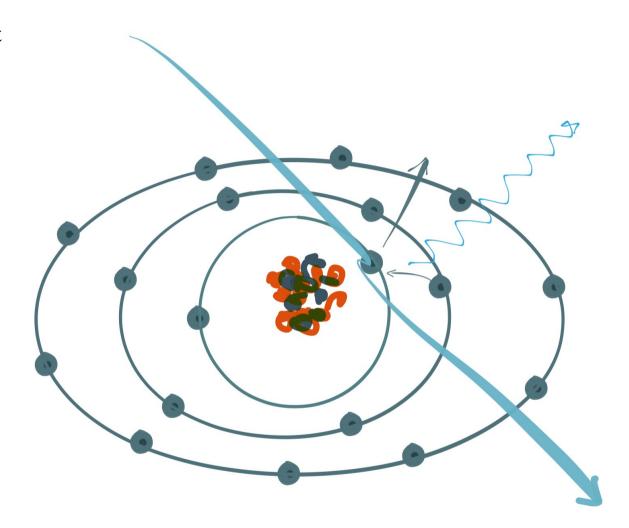
X-ray emission (Bremsstrahlung)

- X-ray emission sent out when an electron is accelerated.
- No elemental information.
- Forms background in EDX.

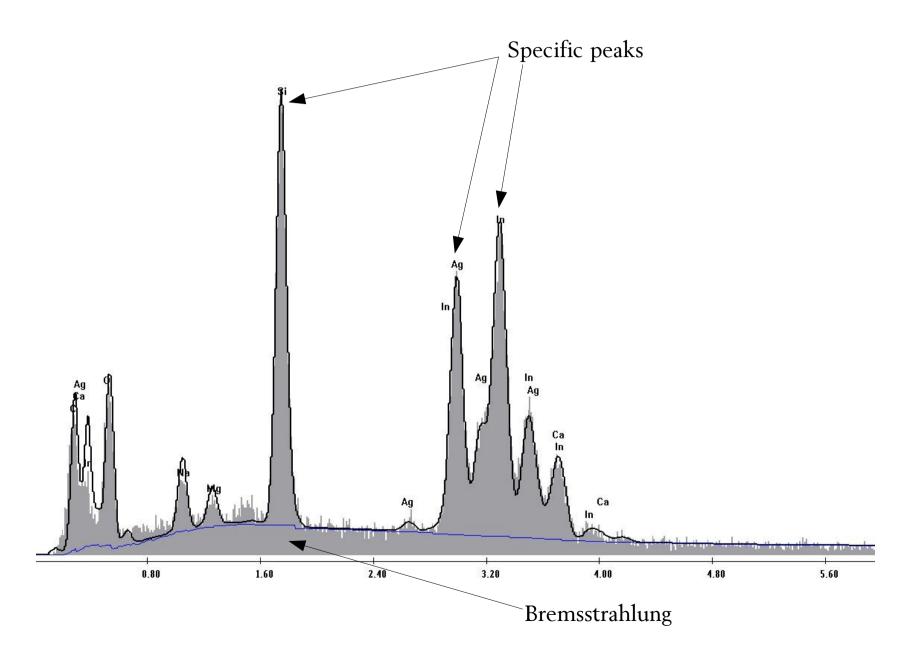


X-ray emission

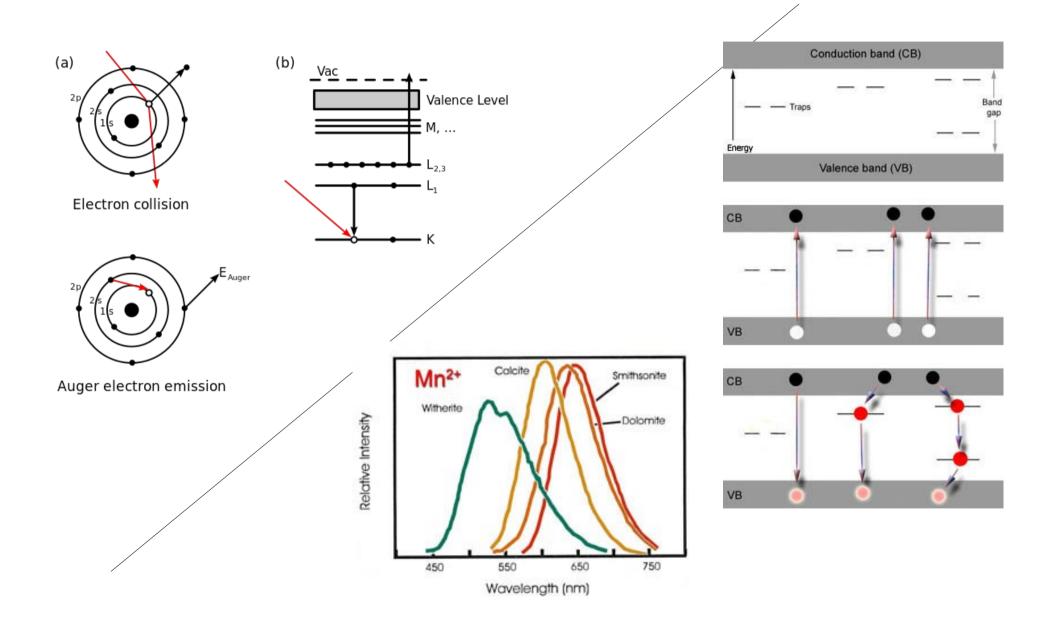
- X-ray emission sent out when an electron emitted from an inner shell and another outer electron fills the hole
- Specific elemental information.
- Basis of EDX.



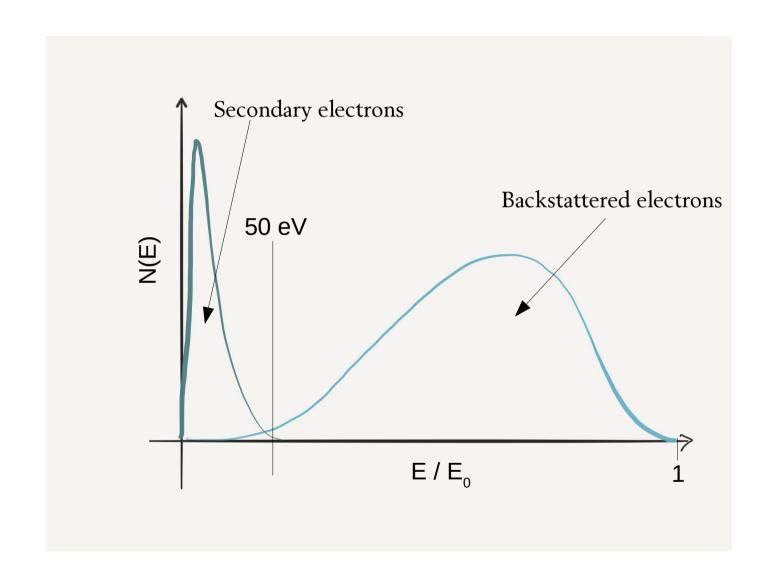
X-ray emission



Auger electrons / CL

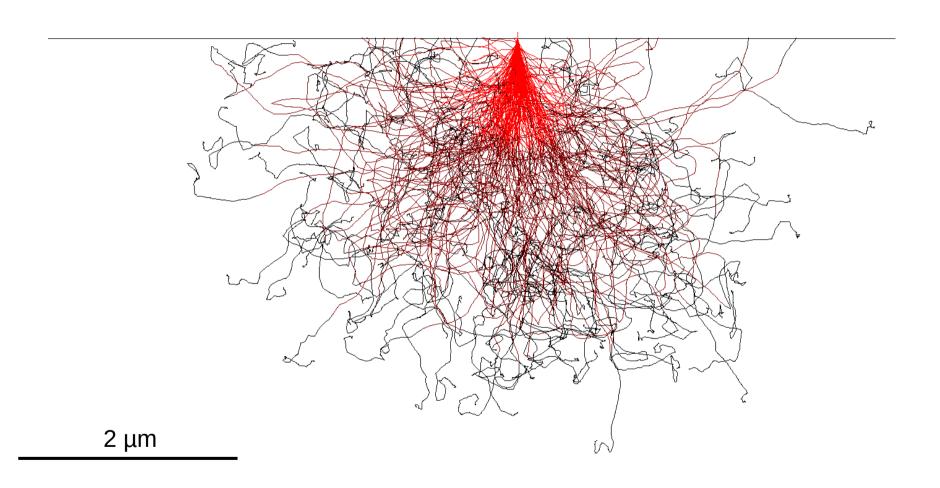


"Types" of electrons

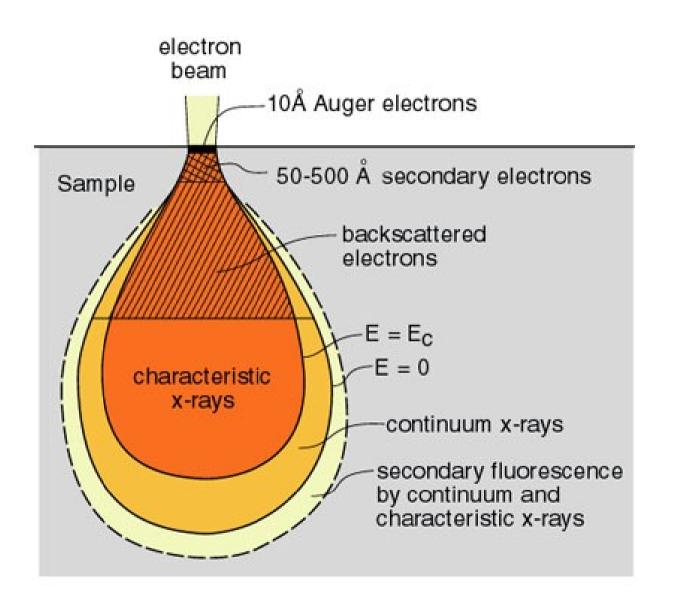


Interaction volume

20 kV beam in Si



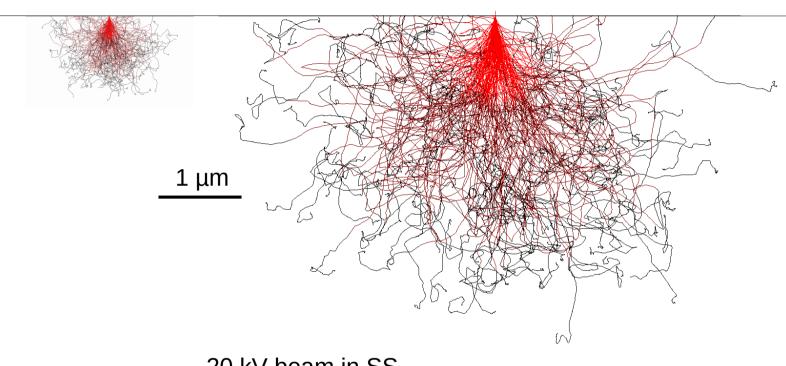
Interaction volume



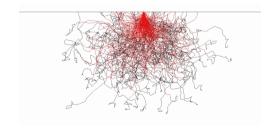
Interaction volume

2 kV beam in Si 10 kV beam in Si

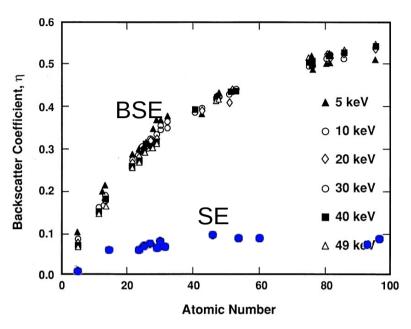
20 kV beam in Si



20 kV beam in SS

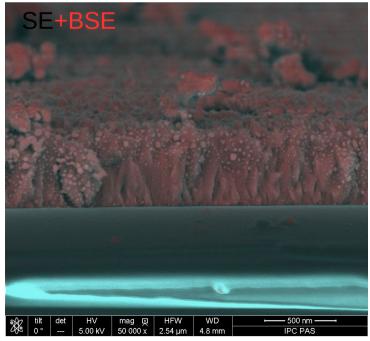


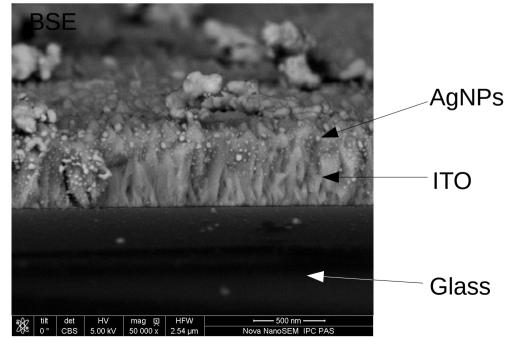
Backscatter efficiency



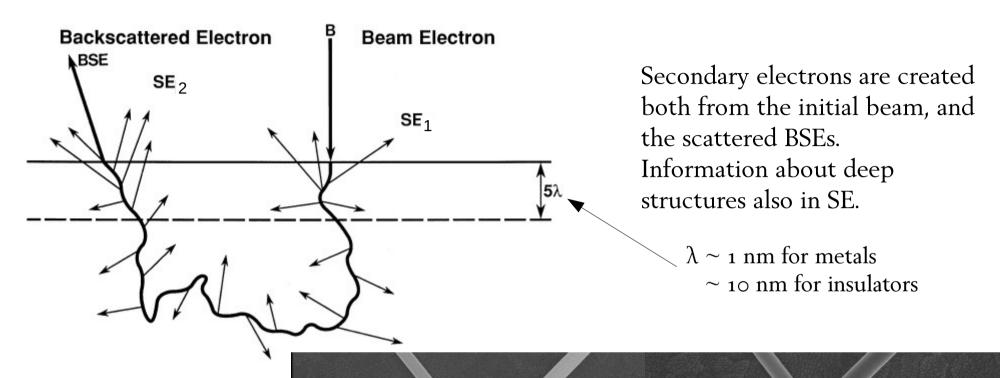
Backscatter efficiency is element dependent, but relatively insensitive to energy.

$$C = \frac{\eta_1 - \eta_2}{\eta_2} \qquad \eta = \sum_i C_i \eta_i,$$



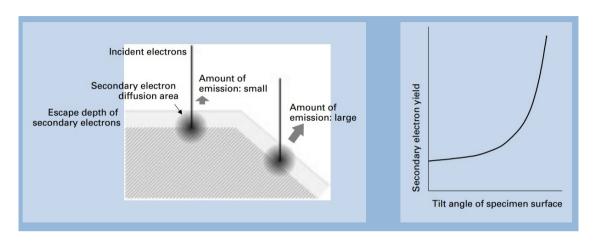


Secondary electons



SE images of nanowires with different acceleration voltages.

Secondary electrons



SE yield is strongly angle dependent.

 \rightarrow bright sides of structures

Edge effect also gives oversaturated edges.

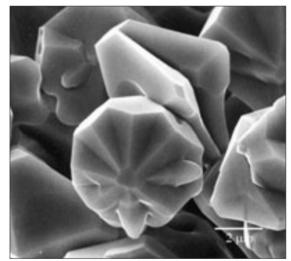
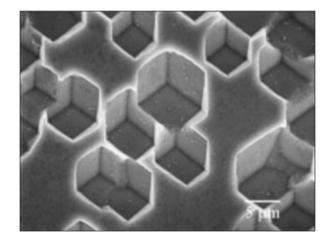
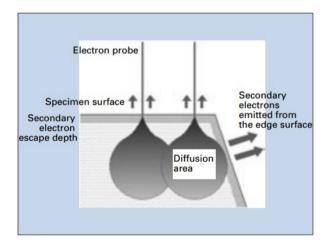


Fig. 15 Secondary electron image of tungsten oxide crystal.





Charging

Charging occurs when the sample, or part of the sample, is not sufficiently conductive.

- → Anomalous contrast
 Too bright, too dark. Often changing over time
- → Distortion

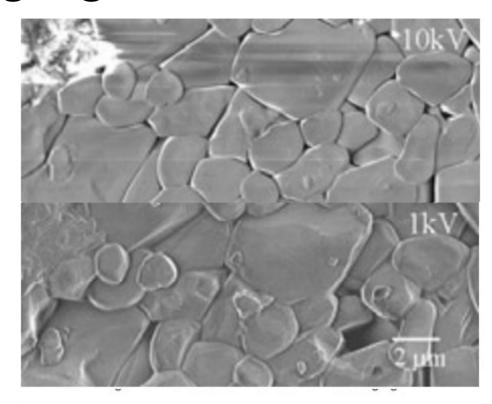
Table 3.5. Secondary Emission as a Function of Energy^a

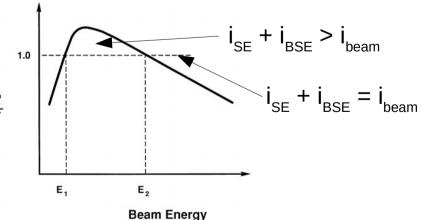
Element	5 keV	20 keV	50 keV
Al	0.4	0.1	0.05
Au	0.7	0.2	0.10

^a After Reimer and Tollkamp (1980).

Table 3.6. Upper Crossover Energy for Various Materials (Normal Beam Incidence)

	Service Control of the Control of th		
Material	$E_2(\text{keV})$	Reference	
Kapton	0.4	Joy (unpublished)	
Electron resist	0.55-0.70	Joy(1987)	
Nylon	1.18	Joy (unpublished)	
5% PB7/nylon	1.40	Krause et al. (1987)	
Acetal	1.65	Vaz (1986)	
Polyvinyl chloride	1.65	Vaz (1986)	
Teflon	1.82	Vaz and Krause (1986)	
Glass passivation	2.0	Joy (1987)	
GaAs	2.6	Joy (1987)	
Quartz	3.0	Joy (1987)	
Alumina	4.2	Joy (unpublished)	





How to avoid charging?

- Lower voltage
- Lower current
- Faster scanning & image integration
- Line interlacing
- Tilting the sample
- BSE instead of SE
- Low vacuum mode
- Coating the sample